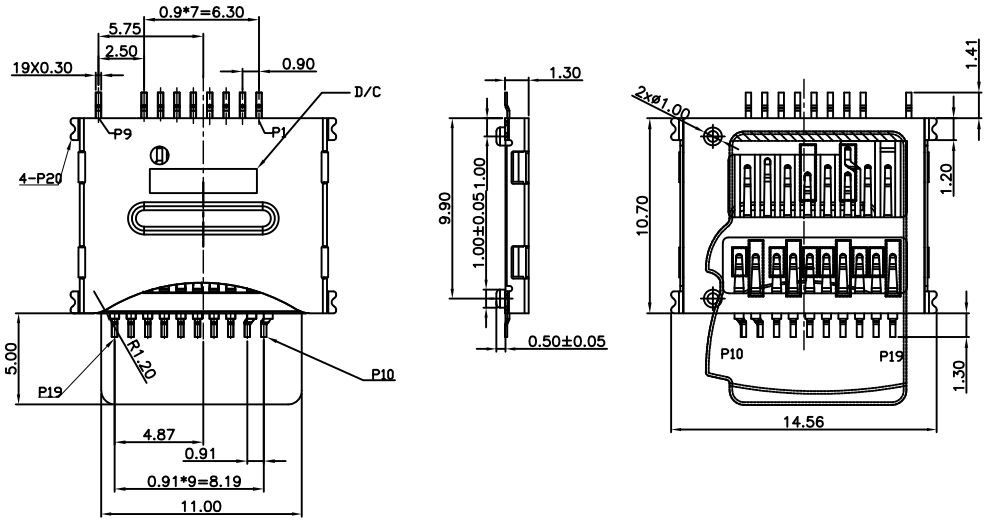
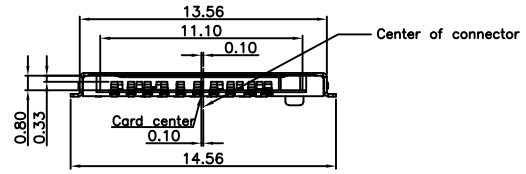
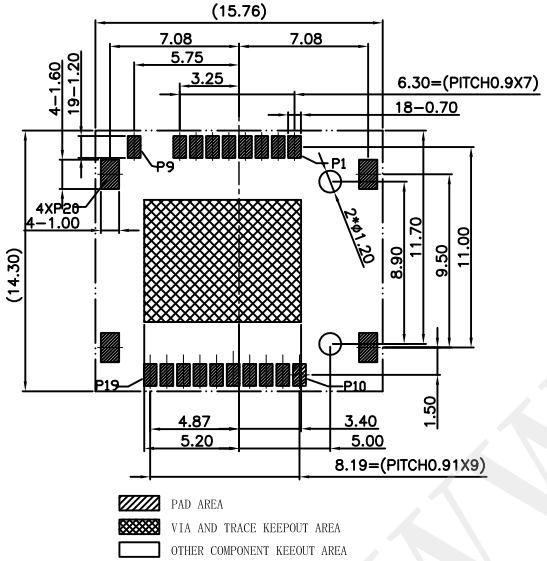
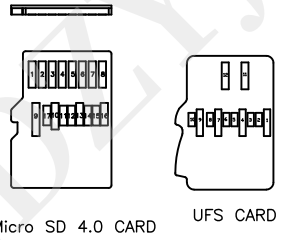








Pin Define

Connector PinNo.	MicroSD 4.0 Card Pin No.	Micro SD with UHS-II and SWIO support			UFS Card	
		Name	Type	Description	Card Pin No.	Name
P1	P1	DAT2	I/O	Data Line[Bit 2]		
P2	P2	CD/DAT3	I/O	Card Detect/Data Line[Bit 3]		
P3	P3	CMD	I/O	Command/Response		
P4	P4	V_{DD1}	S	Supply voltage(3.3V)	P12	VCC
P5	P5	CLK	I	Clock		
P6	P6	V_{SS}	S	Supply voltage ground	P11	VSS
P7	P7	DAT0/RCLK+	I/O	Data Line[Bit 0]/RCLK+		
P8	P8	DAT1/RCLK-	I/O	Data Line[Bit 1]/RCLK-		
P9		CD				CD
P10					P10	C/D(GND)
P11	P9	V_{DD2}	S	Supply voltage(1.8V)	P9	VCCQ2
P12	P17	SWIO	I	Single Wire Protocol Interface	P8	REF_CLK
P13	P10	V_{SS}	S	Supply voltage ground	P7	VSS
P14	P11	D0+	I/O	UHS-II D0+	P6	DOUT_T
P15	P12	D0-	I/O	UHS-II D0-	P5	DOUT_C
P16	P13	V_{SS}	S	Supply voltage ground	P4	VSS
P17	P14	D1-	I/O	UHS-II D1-	P3	DIN_T
P18	P15	D1+	I/O	UHS-II D1+	P2	DIN_C
P19	P16	V_{SS}	S	Supply voltage ground	P1	VSS
P20	GND		GROUND		GND	GROUND

NOTES:
(1)MATERIAL:
1-1.PLASTIC: LCP,THERMOPLASTIC UL 94V-0 COLOR:BLACK
1-2.CONTACT:COPPEER ALLOY C5210-H T=0.12mm
1-3.SHELL:BASS C2680 T=0.15mm
(2)PLATING:
2-1.CONTACT:
2-1-1.CONTACT AREA: Au G/F PLATING OVER Ni
2-1-2.SOLDERTAIL AREA:MATTE TIN 80~100u" OVER Ni
2-2.SHELL:
2-2-1.SOLDERABLE Ni PLATING OVER ALL
(3)CONTACT AND TAIL COPLANARITY TO BE 0.10mm MAX

深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30, X.XX ±0.25, X.XXX ±0.15, X.° ±2°, X.X° ±0.5°	DRAWED BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 1.3H 三合一卡座(TF CARD 4.0+TF CARD+UFS)
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC83-3IN119-130
UNIT: mm [inch]			MOLD NO.
	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2611021209
SCALE:1:1 SIZE: A4			SHEET NO. 1 OF 1

WWW.DZYJZJ.COM